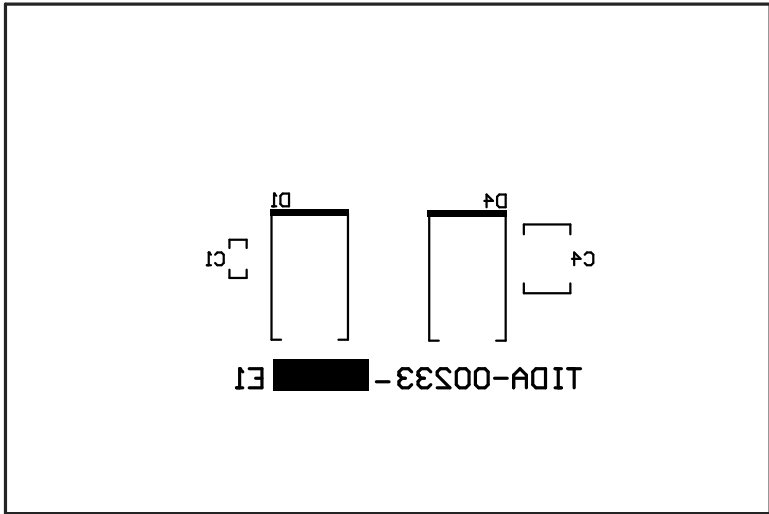
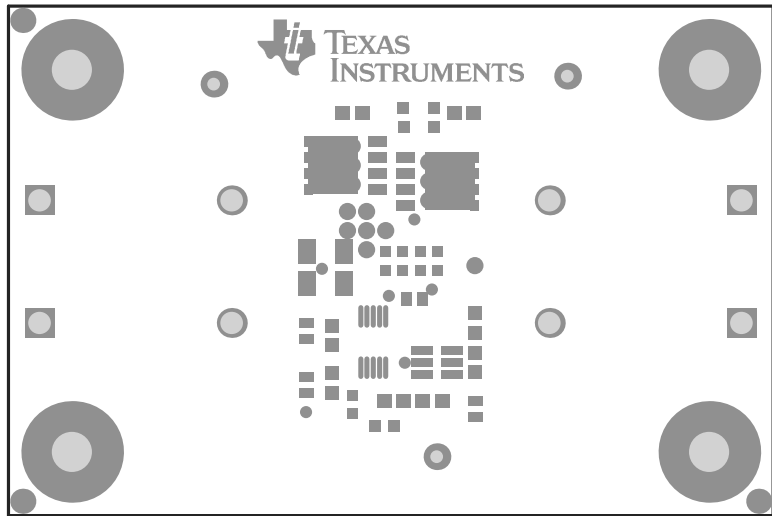


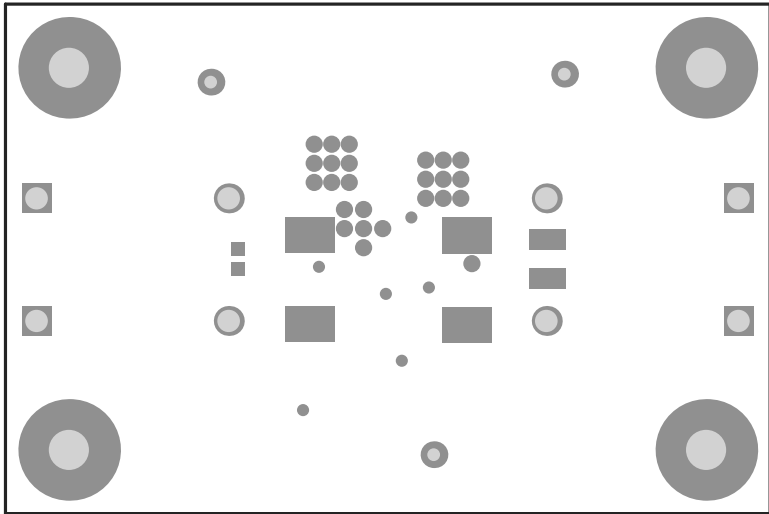
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00233	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/27/2014	3:43:22 PM	TEXAS INSTRUMENTS



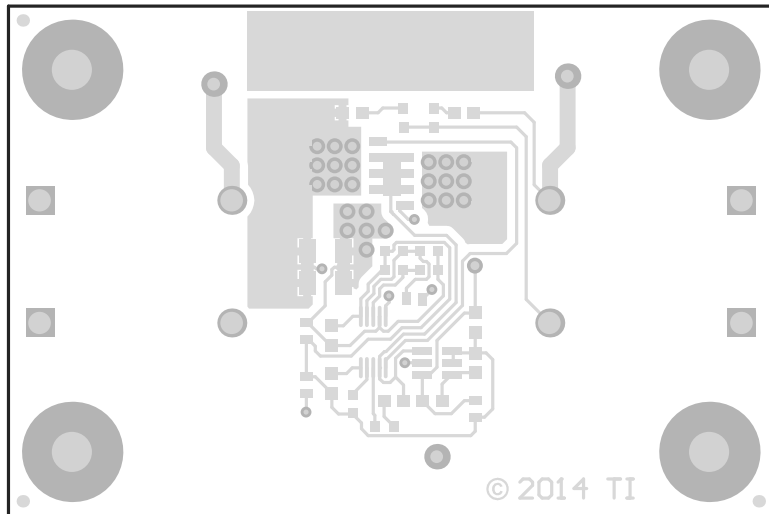
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00233	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 6/27/2014	3:43:22 PM	TEXAS INSTRUMENTS



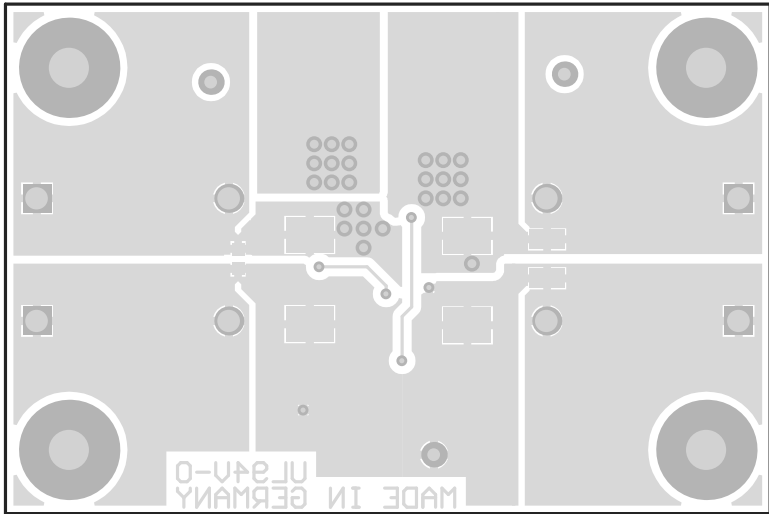
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00233	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/27/2014 3:43:22 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00233	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/27/2014 3:43:23 PM	TEXAS INSTRUMENTS	

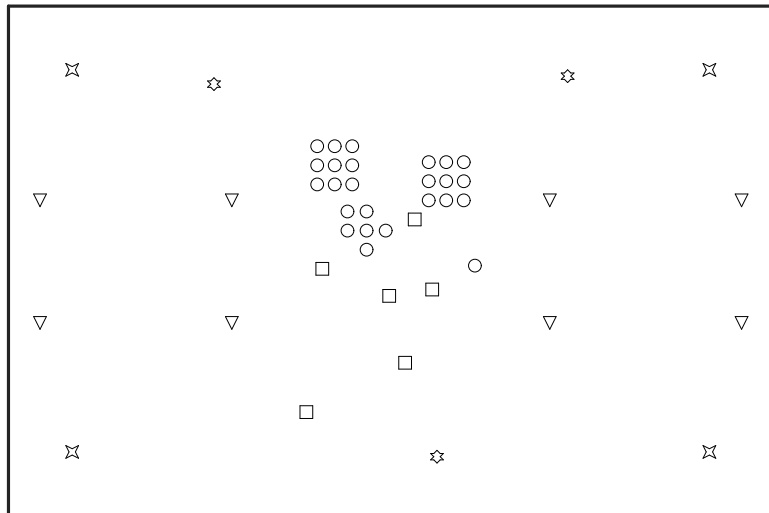


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00233	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/27/2014 3:43:23 PM	TEXAS INSTRUMENTS	



SUN:Not In VersionControl

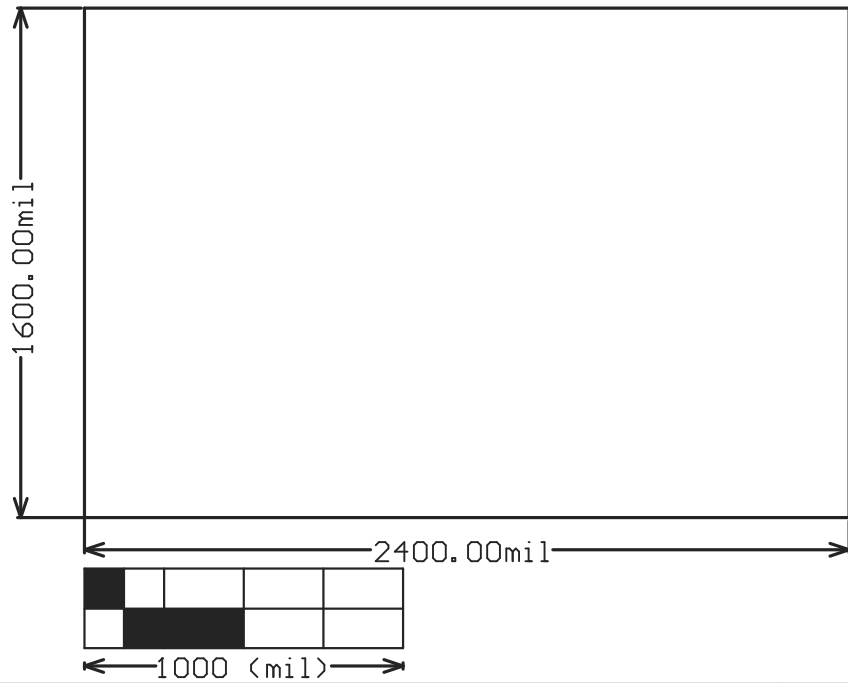
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00233	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 6/27/2014	3:43:24 PM	TEXAS INSTRUMENTS



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	6	16mil (0.406mm)	PTH	Round
○	25	28mil (0.711mm)	PTH	Round
☆	3	40mil (1.016mm)	PTH	Round
▽	8	70.866mil (1.8mm)	PTH	Round
✧	4	125.984mil (3.2mm)	PTH	Round
46 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00233	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/27/2014	3:43:24 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00233	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/27/2014 3:43:25 PM	TEXAS INSTRUMENTS	

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